I'm reaching out to offer your publication an exclusive opportunity to unveil an exciting new development in the semiconductor industry - the appointment of Herman Itzkowiitz as the Chief Technology Officer (CTO) of Microcircuit Laboratories (MCL)
For Immediate Release

Herman Itzkowiitz joins MCL as Chief Technology Officer
March 24, 2024

Microcircuit Laboratories (MCL) is pleased to announce that Herman Itzkowitz is joining MCL as the Chief Technology Officer (CTO). Herman will lead the development and implementation of MCL's technology to deliver innovation and enhance customer deliverables.

"We are thrilled to have Herman on board as our new CTO," Says MCL's Rich Richardson. "With his 25 years of expertise in the semiconductor industry, including processing, manufacturing, and business, we are confident that he will play a pivotal role in helping us meet the evolving needs of our customers."

Herman brings a wealth of experience to his new role, having served as the Chief Executive Officer of SSEC, a company later acquired by VEECO in 2015. His successful integration of technology and operations with VEECO PSP is a testament to his leadership skills. Before this, he held the positions of Chief Technical Officer and Executive Vice President at SSEC. His engineering management roles at DPIX, a DuPont/Xerox joint venture, and QUAD systems further demonstrate his expertise in the field.

Herman expressed his enthusiasm for his new role, stating, "I am gratified to join MCL and contribute to its technological advancement. I look forward to collaborating with the team to drive innovation and deliver superior solutions to our customers."

Since 2015, MCL has delivered complete hermetic package solutions. Our solutions include Photonic packaging, covers with wide area windows, packages with multiple feed-throughs, and full prototyping services, including tests. MCL's pending Robotic Cover Sealer (RCS) patent delivers a fully automated cover seal processor. The RCS is an intelligent machine with no special tooling required. Capabilities include HVM utilizing existing package assembly tooling. MCL is in the Brandywine River Valley of Pennsylvania.